

Title (en)

METHOD AND DEVICE FOR SETTING CONNECTING ELEMENTS THAT ARE SELF-DRILLING WITHOUT CHIP FORMATION

Title (de)

VERFAHREN UND VORRICHTUNG ZUM SETZEN VON SPANLOS SELBSTLOCHFORMENDEN VERBINDUNGSELEMENTEN

Title (fr)

PROCÉDÉ ET DISPOSITIF POUR METTRE EN PLACE DES ÉLÉMENTS DE LIAISON AUTO-TARAUDANTS SANS ENLÈVEMENT DE MATIÈRE

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Application

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Abstract (en)

[origin: CA2804291A1] The invention relates to a method for setting connecting elements (16), such as screws or blind rivets, which are self-drilling without chip formation, in one or more plates, wherein the plate(s) are heated by electrical energy shortly before the start of the setting process, wherein the heating is accomplished by means of an induction coil (26), which is arranged near a point on the plate(s) at which the connecting element (16) is set. The invention further relates to a device (10) for setting a connecting element (16), which is self-drilling without chip formation, in one or more plates, comprising an induction coil (26), which at least before and/or during the setting process is arranged near a point on the plate(s), at which the connecting element (16) is set.

IPC 8 full level

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